MICROWAVE POWER GaAs FET

Internally Matched Power GaAs FETs (X, Ku-Band)

Features

- High power
 - $P_{1dB} = 36.5 \text{ dBm}$ at 14.0 GHz to 14.5 GHz
- High gain
- G_{1dB} = 6.5 dB at 14.0 GHz to 14.5 GHz
 Broad Band Internally Matched
- · Hermetically sealed package

RF Performance Specifications ($T_a = 25^{\circ} C$)

Characteristics	Symbol	Condition	Unit	Min.	Тур.	Max
Output Power at 1dB Compression Point	P _{1dB}		dBm	36.0	36.5	-
Power Gain at 1dB Compression Point	G _{1dB}	V _{DS} = 9V f = 14.0 ~ 14.5 GHz	dB	6.0	6.5	-
Drain Current	I _{DS}		А	_	1.7	2.2
Power Added Efficiency	η _{add}		%	_	23	_
Channel-Temperature Rise	ΔT_{ch}	V _{DS} X I _{DS} X R _{th(c-c)}	°C	_	-	70

Electrical Characteristics (T_a = 25° C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Max
Trans-conductance	gm	V _{DS} =3V I _{DS} =2.0 A	mS	-	1200	-
Pinch-off Voltage	V_{GSoff}	V _{DS} =3V I _{DS} =60mA	V	-2.0	-3.5	-5.0
Saturated Drain Current	I _{DSS}	V _{DS} =3V V _{GS} =0V	А	_	4.0	5.2
Gate to Source Breakdown Voltage	V_{GSO}	I _{GS} =-60 μA	V	-5	_	_
Thermal Resistance	R _{th (c-c)}	Channel to case	°C/W	_	2.9	3.5

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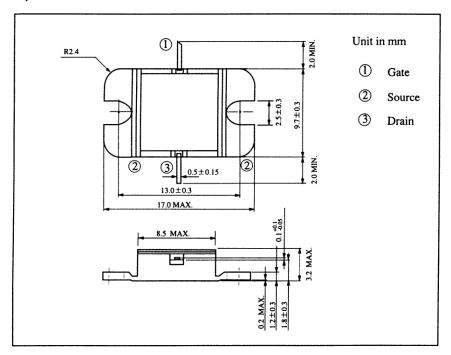
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Absolute Maximum Ratings ($T_a = 25^{\circ} C$)

Characteristic	Symbol	Unit	Rating
Drain Source Voltage	V _{DS}	V	15
Gate Source Voltage	V _{GS}	V	-5
Drain Current	I _{DS}	А	5.2
Total Power Dissipation (Tc = 25°C)	P _T	W	30
Channel Temperature	T _{ch}	°C	175
Storage Temperature	T _{stg}	°C	-65~175

Package Outline (2-9D1B)



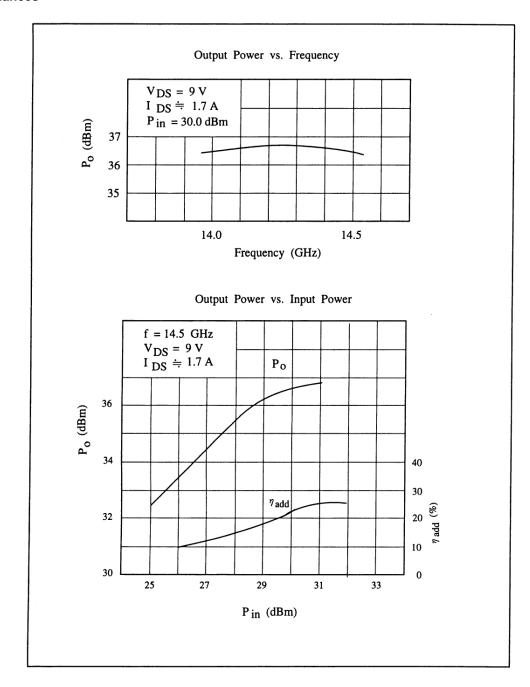
Handling Precautions for Packaged Type

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

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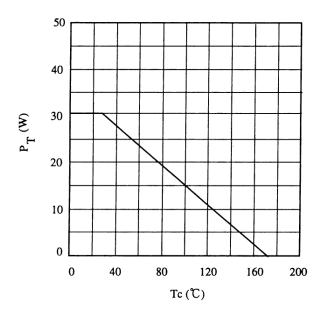
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RF Performances



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Power Dissipation vs. Case Temperature



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